

PATENT 0763-0173P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

Dong Kyun SOHN et al. Conf.:

9674

Appl. No.:

10/620,608

Group:

2814

Filed:

July 17, 2003

Examiner: L. PHAM

For:

METHOD OF FORMING FILM FOR REDUCED OHMIC CONTACT RESISTANCE AND TERNARY PHASE LAYER AMORPHOUS DIFFUSION BARRIER

(To be Amended)

LARGE ENTITY TRANSMITTAL FORM

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 June 3, 2004

Sir:

Transmitted herewith is an amendment in the above-identified application.

The enclosed	document i	is k	peing	transm	nitted	via	the	Certificate
of Mailing p	rovisions	of	37 C.	F.R. §	1.8.			

The enclosed document is being transmitted via facsimile.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR		PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	5	-	- 20		0	\$ 18	\$0.00
INDEPENDENT	2	-	3	=	0	\$ 86	\$0.00
FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM						\$290	\$0.00
						TOTAL	\$0.00

(Rev. 02/08/2004)

		month(s) extension of time pursuant to $1.136(a)$. $\$0.00$ for the extension of						
\boxtimes	No fee is required.							
	Check(s) in the amount of \$0.00 is(are) enclosed.							
	Please charge Deposit Account No. 02-2448 in the amount of \$0.00. This form is submitted in triplicate.							
If necessary, the Commissioner is hereby authorized in this concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional feet required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17 particularly, extension of time fees.								
		Respectfully submitted,						
		BIRCH, STEWART, KOLASCH & BIRCH, LLP By Ame (Classe)						
		James T. Eller, Jr./, #39,538 P.O. Box 747						
JTE: 0763	cms -0173P	Falls Church, VA 22040-0747 (703) 205-8000						
Atta	chment(s)							



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Amended)

AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

June 3, 2004

Sir:

In response to the Examiner's Office Action dated March 3, 2004, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Title of the Invention

Please change the Title of the Invention to --SEMICONDUCTOR

DEVICE INCLUDING TERNARY PHASE DIFFUSION BARRIER--.